Abstract

1.1 Method and device for processing substrates

2.1 During the processing of substrates (1) in a number of automatic processing machines (6, 8) arranged one behind another, the position co-ordinates of the substrates (1) and additional geometric data about circuit markings or functional markings are determined in each automatic processing machine (6, 8) and are used for the processing.

2.2 According to the invention, the geometric data are determined only in the first automatic processing machine (6) and are transmitted to the second automatic processing machine (8) via a bus system (13), and are used in the second automatic processing machine (8), which leads to a lower expenditure on time.

2.3 Pick-and-place robots.

FIG. 2